

## Low-Noise LVDS Clock Generator

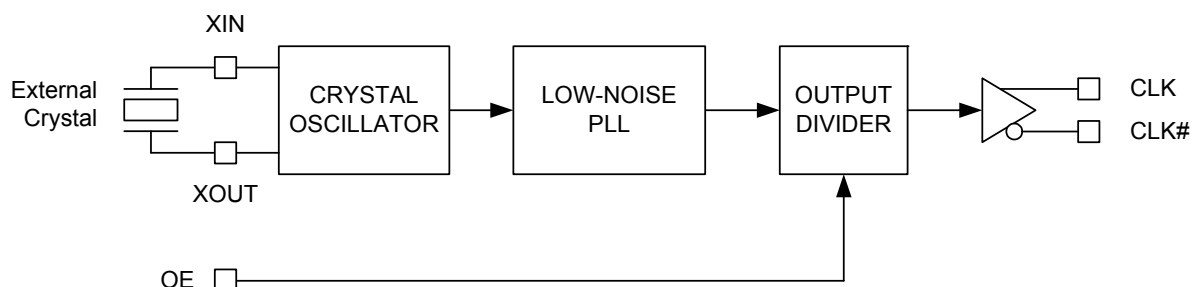
### Features

- Output: One low-voltage differential signal (LVDS) output pair
- Output frequency: 125 MHz
- Input: 25-MHz external crystal
- RMS phase jitter:
  - At 125 MHz (12 kHz to 20 MHz offset): 0.65 ps typical
- Package: Pb-free 8-pin thin shrunk small outline package (TSSOP)
- Supply voltage: 3.3 V or 2.5 V
- Temperature range: Commercial or industrial

### Functional Description

The CY2XL13 is a phase-locked loop (PLL)-based high-performance clock generator that uses Cypress's low-noise voltage control oscillator (VCO) technology to achieve less than 1-ps typical RMS phase jitter. The CY2XL13 uses an external crystal reference input to generate one LVDS output pair, which can be asynchronously enabled/disabled with an OE pin. The device operates at 3.3 V or 2.5 V.

### Logic Block Diagram



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## Pinout

Figure 1. 8-pin TSSOP pinout



## Pin Definitions

8-pin TSSOP

| Pin Number | Pin Name  | I/O Type              | Description                                                                              |
|------------|-----------|-----------------------|------------------------------------------------------------------------------------------|
| 1, 8       | VDD       | Power                 | 3.3-V or 2.5-V power supply. All supply current flows through pin 1                      |
| 2          | VSS       | Power                 | Ground                                                                                   |
| 3, 4       | XOUT, XIN | XTAL output and input | Parallel resonant crystal interface                                                      |
| 5          | OE        | CMOS input            | Output enable: When high, the output is enabled. When low, the output is high impedance. |
| 6, 7       | CLK#, CLK | LVDS output           | Differential clock output                                                                |

## Frequency Table

| Part Number  | Crystal Frequency | Output Frequency | Pin 5 Function | RMS Phase Jitter (Random) |                  |
|--------------|-------------------|------------------|----------------|---------------------------|------------------|
|              |                   |                  |                | Offset Range              | Jitter (Typical) |
| CY2XL13ZXC01 | 25 MHz            | 125 MHz          | OE             | 12 kHz to 20 MHz          | 0.65 ps          |
| CY2XL13ZXI01 |                   |                  |                |                           |                  |

## Absolute Maximum Conditions

| Parameter                      | Description                                                 | Condition                   | Min  | Max                   | Unit |
|--------------------------------|-------------------------------------------------------------|-----------------------------|------|-----------------------|------|
| V <sub>DD</sub>                | Supply voltage                                              |                             | −0.5 | 4.4                   | V    |
| V <sub>IN</sub> <sup>[1]</sup> | Input voltage, DC                                           | Relative to V <sub>SS</sub> | −0.5 | V <sub>DD</sub> + 0.5 | V    |
| T <sub>S</sub>                 | Temperature, Storage                                        | Non operating               | −65  | 150                   | °C   |
| T <sub>J</sub>                 | Temperature, Junction                                       |                             | −    | 135                   | °C   |
| ESD <sub>HBM</sub>             | Electrostatic discharge (ESD) protection (human body model) | JEDEC STD 22-A114-B         | 2000 | −                     | V    |
| UL−94                          | Flammability rating                                         | At 1/8 in.                  | V−0  |                       | −    |
| Θ <sub>JA</sub> <sup>[2]</sup> | Thermal resistance, junction to ambient                     | 0 m/s airflow               | 100  |                       | °C/W |
|                                |                                                             | 1 m/s airflow               | 91   |                       |      |
|                                |                                                             | 2.5 m/s airflow             | 87   |                       |      |

## Operating Conditions

| Parameter | Description                                                                                        | Min   | Max   | Unit |
|-----------|----------------------------------------------------------------------------------------------------|-------|-------|------|
| $V_{DD}$  | 3.3-V supply voltage                                                                               | 3.135 | 3.465 | V    |
|           | 2.5-V supply voltage                                                                               | 2.375 | 2.625 | V    |
| $T_A$     | Ambient temperature, commercial                                                                    | 0     | 70    | °C   |
|           | Ambient temperature, industrial                                                                    | −40   | 85    | °C   |
| $T_{PU}$  | Power-up time for all $V_{DD}$ to reach minimum specified voltage (ensure power ramp is monotonic) | 0.05  | 500   | ms   |

### Notes

1. The voltage on any input or I/O pin cannot exceed the  $V_{DD}$  pins during power-up.
2. Simulated using Apache Sentinel TI software. The board is derived from the JEDEC multilayer standard. It measures 76 x 114 x 1.6 mm and has 4-layers of copper (2/1/1/2 oz.). The internal layers are 100% copper planes, while the top and bottom layers have 50% metallization. No vias are included in the model.

## DC Electrical Characteristics

| Parameter             | Description                                            | Test Conditions                                                                                   | Min                 | Typ | Max                 | Unit          |
|-----------------------|--------------------------------------------------------|---------------------------------------------------------------------------------------------------|---------------------|-----|---------------------|---------------|
| $I_{DD}^{[3]}$        | Power supply current with output terminated            | $V_{DD} = 3.465\text{ V}$ , $OE = V_{DD}$ , output terminated                                     | –                   | –   | 120                 | mA            |
|                       |                                                        | $V_{DD} = 2.625\text{ V}$ , $OE = V_{DD}$ , output terminated                                     | –                   | –   | 115                 | mA            |
| $V_{OD}^{[4]}$        | LVDS differential output voltage                       | $V_{DD} = 3.3\text{ V}$ or $2.5\text{ V}$ , $R_{TERM} = 100\ \Omega$ between CLK and CLK#         | 247                 | –   | 454                 | mV            |
| $\Delta V_{OD}^{[4]}$ | Change in $V_{OD}$ between complementary output states | $V_{DD} = 3.3\text{ V}$ or $2.5\text{ V}$ , $R_{TERM} = 100\ \Omega$ between CLK and CLK#         | –                   | –   | 50                  | mV            |
| $V_{OS}^{[5]}$        | LVDS offset output voltage                             | $V_{DD} = 3.3\text{ V}$ or $2.5\text{ V}$ , $R_{TERM} = 100\ \Omega$ between CLK and CLK#         | 1.125               | –   | 1.375               | V             |
| $\Delta V_{OS}$       | Change in $V_{OS}$ between complementary output states | $V_{DD} = 3.3\text{ V}$ or $2.5\text{ V}$ , $R_{TERM} = 100\ \Omega$ between CLK and CLK#         | –                   | –   | 50                  | mV            |
| $I_{OZ}$              | Output leakage current                                 | Three-state output, unterminated, measured on one pin while floating the other pin, $OE = V_{SS}$ | –35                 | –   | 35                  | $\mu\text{A}$ |
| $V_{IH}$              | Input high voltage, pin 5                              |                                                                                                   | $0.7 \times V_{DD}$ | –   | –                   | V             |
| $V_{IL}$              | Input low voltage, pin 5                               |                                                                                                   | –                   | –   | $0.3 \times V_{DD}$ | V             |
| $I_{IH}$              | Input high current, pin 5                              | Input = $V_{DD}$                                                                                  | –                   | –   | 115                 | $\mu\text{A}$ |
| $I_{IL}$              | Input low current, pin 5                               | Input = $V_{SS}$                                                                                  | –50                 | –   | –                   | $\mu\text{A}$ |
| $C_{IN}$              | Input capacitance, pin 5                               |                                                                                                   | –                   | 15  | –                   | pF            |
| $C_{INX}$             | Pin capacitance, XIN and XOUT                          |                                                                                                   | –                   | 4.5 | –                   | pF            |

### Notes

3.  $I_{DD}$  includes ~4 mA of current that is dissipated externally in the output termination resistor.
4. Refer to [Figure 2 on page 7](#).
5. Refer to [Figure 3 on page 7](#).

## AC Electrical Characteristics

| Parameter <sup>[6, 7]</sup>  | Description               | Test Conditions                                                                     | Min        | Typ | Max | Unit |
|------------------------------|---------------------------|-------------------------------------------------------------------------------------|------------|-----|-----|------|
| $F_{OUT}^{[8]}$              | Output frequency          |                                                                                     | See note 8 |     |     | MHz  |
| $T_R, T_F^{[9]}$             | Output rise or fall time  | 20% to 80% of full output swing                                                     | –          | 0.5 | 1.0 | ns   |
| $T_{Jitter(\phi)}^{[8, 10]}$ | RMS phase jitter (random) | Offset = 12 kHz to 20 MHz                                                           | –          | –   | 1.0 | ps   |
| $T_{DC}^{[11]}$              | Duty cycle                | Measured at zero crossing point                                                     | 45         | –   | 55  | %    |
| $T_{OHZ}^{[12]}$             | Output disable time       | Time from falling edge on OE to stopped outputs (asynchronous)                      | –          | –   | 100 | ns   |
| $T_{OE}^{[12]}$              | Output enable time        | Time from rising edge on OE to outputs at a valid frequency (asynchronous)          | –          | –   | 120 | ns   |
| $T_{LOCK}$                   | Startup time              | Time for CLK to reach valid frequency measured from the time $V_{DD} = V_{DD(min)}$ | –          | –   | 5   | ms   |

## Crystal Characteristics

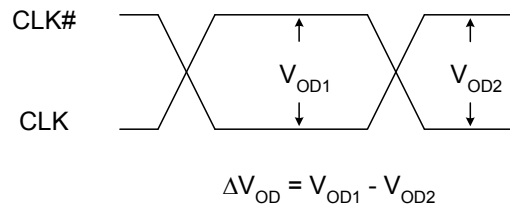
| Parameter | Description                  | Min         | Max | Unit     |
|-----------|------------------------------|-------------|-----|----------|
| MO        | Mode of oscillation          | Fundamental |     |          |
| $F^{[8]}$ | Frequency                    | See note 8  |     | MHz      |
| ESR       | Equivalent series resistance | –           | 50  | $\Omega$ |
| $C_S$     | Shunt capacitance            | –           | 7   | pF       |

### Notes

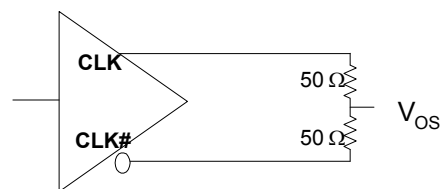
6. Not 100% tested, guaranteed by design and characterization.
7. Outputs are terminated with 100  $\Omega$  between CLK and CLK#. Refer to [Figure 8 on page 8](#).
8. Crystal frequency, output frequency, and typical phase jitter are listed in [Frequency Table on page 3](#).
9. Refer to [Figure 4 on page 7](#).
10. Refer to [Figure 7 on page 8](#).
11. Refer to [Figure 5 on page 7](#).
12. Refer to [Figure 6 on page 7](#).

## Switching Waveforms

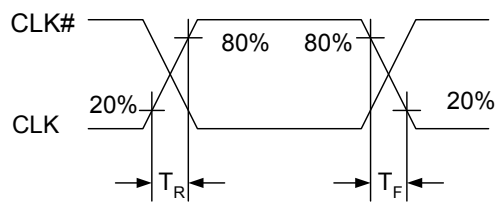
**Figure 2. Output Voltage Swing**



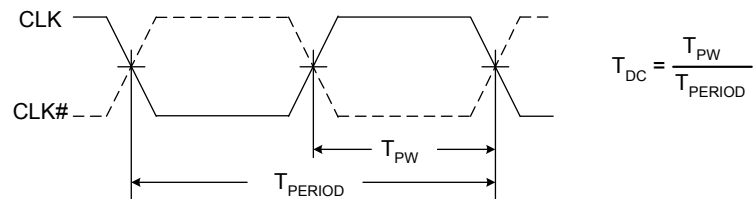
**Figure 3. Output Offset Voltage**



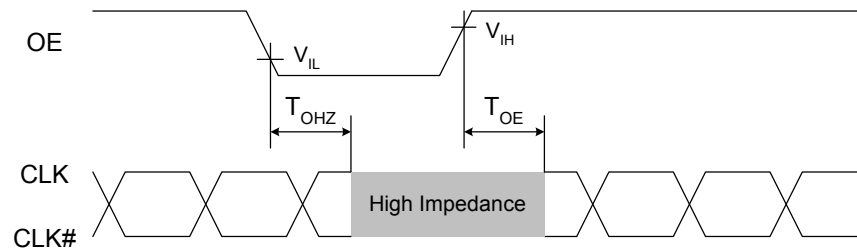
**Figure 4. Output Rise or Fall Time**



**Figure 5. Duty Cycle Timing**

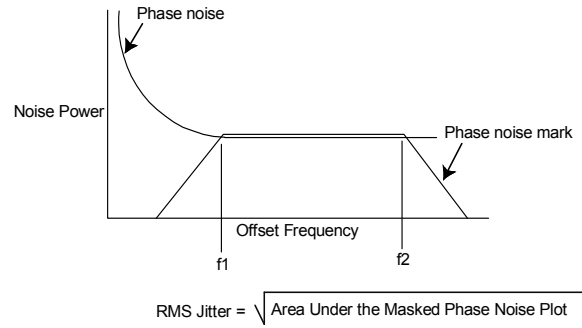


**Figure 6. Output Enable and Disable Timing**



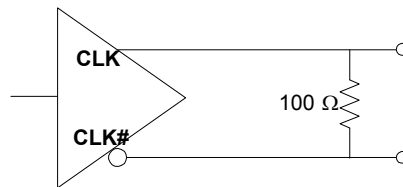
## Switching Waveforms (continued)

**Figure 7. RMS Phase Jitter**



## Termination Circuits

**Figure 8. LVDS Termination**

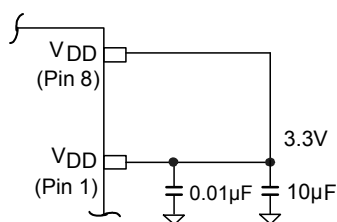


## Application Information

### Power Supply Filtering Techniques

As in any high-speed analog circuitry, noise at the power supply pins can degrade performance. To achieve optimum jitter performance, use good power-supply isolation practices. Figure 9 illustrates a typical filtering scheme. Because all the current flows through pin 1, the resistance and inductance between this pin and the supply is minimized. A 0.01 or 0.1  $\mu\text{F}$  ceramic chip capacitor is also located close to this pin to provide a short and low-impedance AC path to ground. A 1 to 10  $\mu\text{F}$  ceramic or tantalum capacitor is located in the general vicinity of this device and may be shared with other devices.

**Figure 9. Power Supply Filtering**



### Board Layout and OE Pin

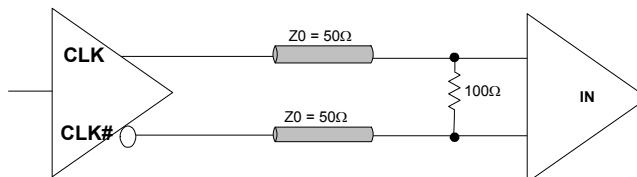
If the Output Enable (OE) function on pin 5 is not needed, it may be connected directly to the  $V_{DD}$  plane by a wide trace and multiple vias. This improves heat dissipation. A resistor between OE and  $V_{DD}$  is not necessary.

### Termination for LVDS Output

The CY2XL13 is designed to drive a standard LVDS load with a 100- $\Omega$  termination resistor. Figure 10 shows the standard termination scheme. The termination resistor should always be

located very close to the receiver. To minimize signal reflections from the receiver, the differential impedance ( $Z_0$ ) of the trace pair should be 100  $\Omega$  to match the termination resistor.

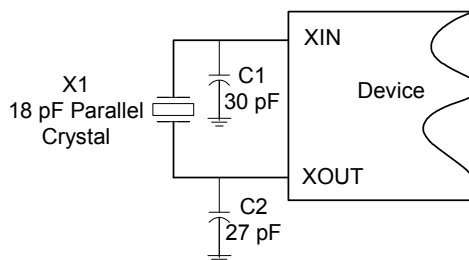
**Figure 10. Output Termination**



### Crystal Interface

The CY2XL13 is characterized with 18 pF parallel resonant crystals. The capacitor values shown in Figure 11 are determined using an 18 pF parallel resonant crystal and are chosen to minimize the ppm error. Note that the optimal values for C1 and C2 depend on the parasitic trace capacitance and are, therefore, layout dependent.

**Figure 11. Crystal Input Interface**





| Part Number   | Package Description         | Product Flow                |
|---------------|-----------------------------|-----------------------------|
| CY2XL13ZXC01  | 8-pin TSSOP                 | Commercial, 0 °C to 70 °C   |
| CY2XL13ZXC01T | 8-pin TSSOP – Tape and Reel | Commercial, 0 °C to 70 °C   |
| CY2XL13ZXI01  | 8-pin TSSOP                 | Industrial, –40 °C to 85 °C |
| CY2XL13ZXI01T | 8-pin TSSOP – Tape and Reel | Industrial, –40 °C to 85 °C |

CY 2XL13 Z X X xx X

X = blank or T  
blank = Tube; T = Tape and Reel

Part configuration code: xx = 01

Temperature Range: X = C or I  
C = Commercial; I = Industrial

Pb-free

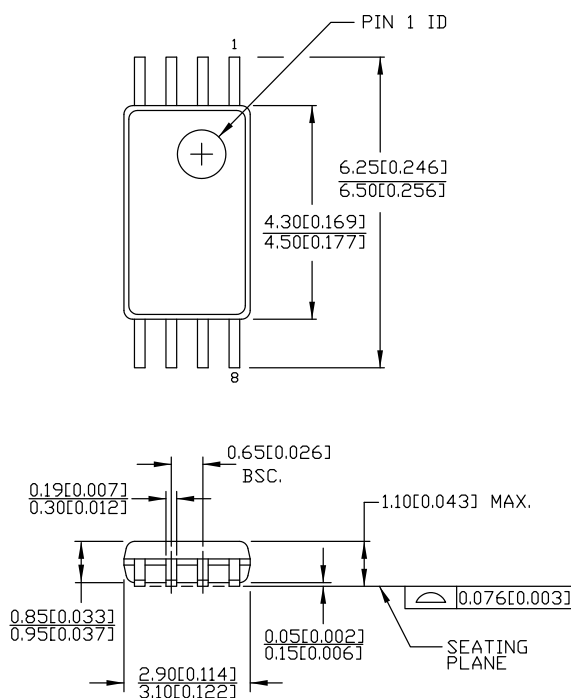
Package Type: Z = 8-pin TSSOP

Base part number

Company ID: CY = Cypress

## Package Drawing and Dimensions

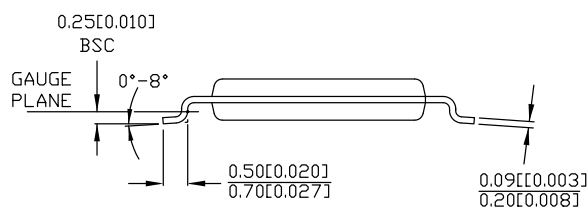
**Figure 12. 8-pin TSSOP (4.40 mm Body) Z08.173/ZZ08.173 Package Outline, 51-85093**



DIMENSIONS IN MM[INCHES] MIN.  
MAX.

REFERENCE JEDEC MO-153

| PART #   |                |
|----------|----------------|
| Z08.173  | STANDARD PKG.  |
| ZZ08.173 | LEAD FREE PKG. |



51-85093 \*D

## Acronyms

| Acronym | Description                                |
|---------|--------------------------------------------|
| ESD     | Electrostatic Discharge                    |
| FAE     | Field Application Engineer                 |
| HBM     | Human Body Model                           |
| JEDEC   | Joint Electron Devices Engineering Council |
| LCC     | Leadless Chip Carrier                      |
| LVDS    | Low-Voltage Differential Signaling         |
| OE      | Output Enable                              |
| PCB     | Printed Circuit Board                      |
| PLL     | Phase-Locked Loop                          |
| RMS     | Root Mean Square                           |
| TSSOP   | Thin Shrunk Small Outline Package          |
| VCO     | Voltage Controlled Oscillator              |
| XO      | Crystal Oscillator                         |

## Document Conventions

### Units of Measure

| Symbol | Unit of Measure |
|--------|-----------------|
| °C     | degree Celsius  |
| MHz    | megahertz       |
| μA     | microampere     |
| μs     | microsecond     |
| mA     | milliampere     |
| mm     | millimeter      |
| ns     | nanosecond      |
| Ω      | ohm             |
| %      | percent         |
| pF     | picofarad       |
| V      | volt            |
| W      | watt            |

## Document History Page

| Document Title: CY2XL13, Low-Noise LVDS Clock Generator<br>Document Number: 001-63177 |         |                 |                 |                                                                                                                                                                              |
|---------------------------------------------------------------------------------------|---------|-----------------|-----------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Rev.                                                                                  | ECN No. | Submission Date | Orig. of Change | Description of Change                                                                                                                                                        |
| **                                                                                    | 2991849 | 07/23/2010      | KVM             | New data sheet.                                                                                                                                                              |
| *A                                                                                    | 4118896 | 09/10/2013      | CINM            | Updated <a href="#">Package Drawing and Dimensions</a> :<br>spec 51-85093 – Changed revision from *C to *D.<br><br>Updated in new template.<br><br>Completing Sunset Review. |

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